



SOT619-13

plastic thermal enhanced very thin quad flat package; no leads; 48 terminals

22 April 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN48
Package type industry code	HVQFN48
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	MO-220
Mounting method type	S (surface mount)
Issue date	27-3-2013

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	6.9	-	7	7.1	mm
E	package width	6.9	-	7	7.1	mm
A	seated height	0.8	-	0.85	1	mm
e	nominal pitch	-	-	0.5	-	mm
n ₂	actual quantity of termination	-	-	48	-	

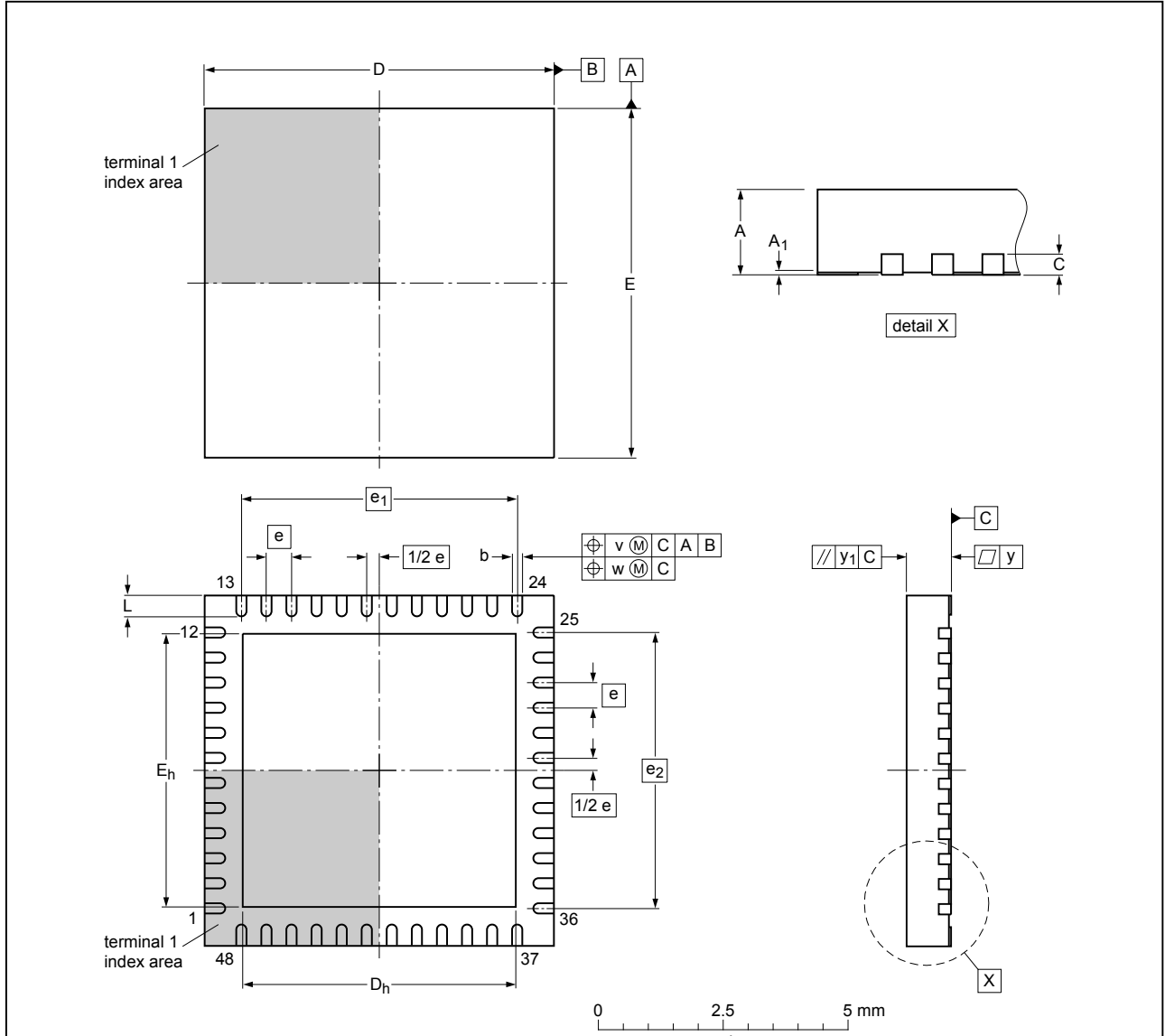


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2. Package outline

HVQFN48: plastic thermal enhanced very thin quad flat package; no leads; 48 terminals; body 7 x 7 x 0.85 mm

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Dimensions (mm are the original dimensions)

Unit ⁽¹⁾	A ⁽¹⁾	A ₁	b	C	D	D _h	E	E _h	e	e ₁	e ₂	L	v	w	y	y ₁
max	1.00	0.05	0.30		7.1	5.65	7.1	5.65				0.5				
mm nom	0.85	0.02	0.21	0.2	7.0	5.50	7.0	5.50	0.5	5.5	5.5	0.4	0.1	0.05	0.05	0.1
min	0.80	0.00	0.18		6.9	5.35	6.9	5.35				0.3				

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included

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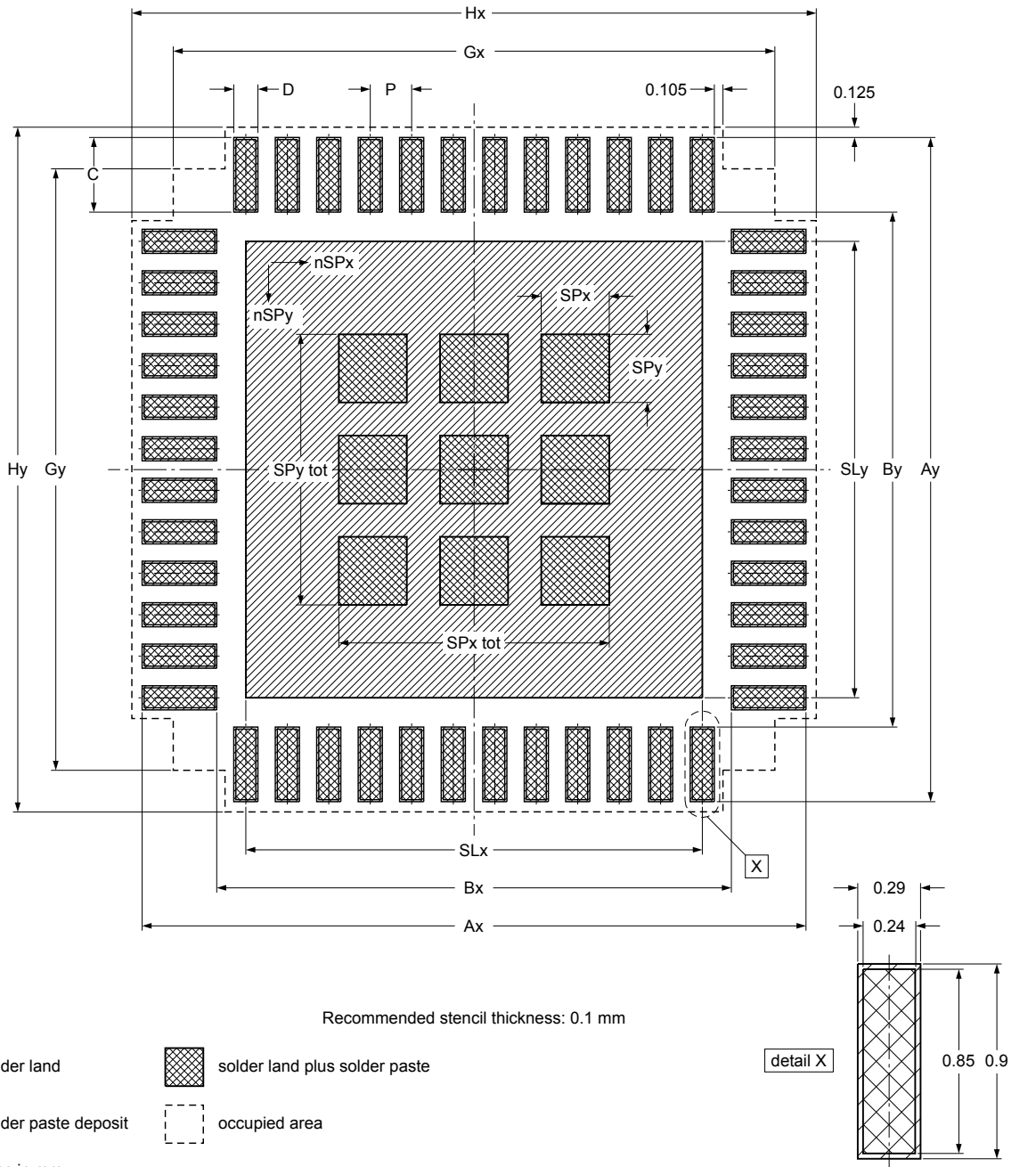
Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT619-13	---	MO-220	---		-09-08-24- 13-03-27

Fig. 1. Package outline HVQFN48 (SOT619-13)

3. Soldering

Footprint information for reflow soldering of HVQFN48 package

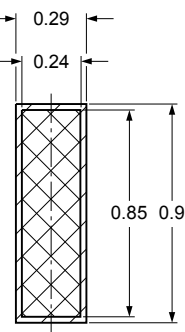
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Recommended stencil thickness: 0.1 mm

- solder land
- solder land plus solder paste
- solder paste deposit
- occupied area

detail X



Dimensions in mm

P	Ax	Ay	Bx	By	SLx	SLy	SPx	SPy	SPx tot	SPy tot	C	D	nSPx	nSPy	Gx	Gy	Hx	Hy
0.50	8.00	8.00	6.20	6.20	5.50	5.50	0.82	0.82	3.26	3.26	0.90	0.29	3	3	7.25	7.25	8.25	8.25

Issue date ~~15-12-10~~
15-12-23

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Fig. 2. Reflow soldering footprint for HVQFN48 (SOT619-13)

4. Legal information

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